



100% Material Declaration Data Sheet BGG560

PK217 (v1.0) February 20, 2007

Material Declaration Data Sheet

Average Weight: 10.243 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.2814	2.75%
	Silicon	7440-21-3	100.00		0.2814	
Die Attach Material					0.0227	0.22%
	Resin	Trade Secret	25.00		0.005675	
	Silver	7440-22-4	75.00		0.017025	
Mold Compound					0.5334	5.21%
	Resin	Trade Secret	26.00		0.138684	
	Silica	60676-86-0	74.00	Filler	0.394716	
Dam					0.0138	0.13%
	Resin	Trade Secret	28.00		0.003864	
	Silica	60676-86-0	72.00	Filler	0.009936	
Laminate					0.8314	8.12%
	BT (core)	Trade Secret			0.509	
	Solder Mask (EP)	Trade Secret			0.180	
	Copper	7440-50-8		Metal Layer	0.129	
	Nickel	7440-02-0		Metal Layer	0.010	
	Gold	7440-57-5		Metal Layer	0.003	
Heat Spreader					7.2427	70.71%
	Copper	7440-50-8	97.50		7.062	
	Iron	7439-89-6	2.35		0.170	
	Phosphorus	7723-14-0	0.03		0.002	
	Zinc	7440-66-6	0.12		0.009	
Heat Spreader Adhesive					0.329	3.21%
	Nickel	7440-02-0	100.00		0.0329	
Gold Wire					0.0236	0.23%
	Gold	74410-57-5	100.00		0.0236	
Solder Balls					0.9648	9.42%
	Tin	7440-31-5	95.50		0.921	
	Silver	7440-22-4	4.0		0.039	
	Copper	7440-50-8	0.5		0.005	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
2/20/07	1.0	Initial release.